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APPLICATION NO.	FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO		
09/709,483	11/13/2000		Oh-Nam Kwon	8733.307.00	4557		
30827	7590	10/24/2003		EXAMINER			
		& ALDRIDGE LI	P .	PHAM, THANH V			
1900 K STR WASHINGT	•			ART UNIT	PAPER NUMBER		
***************************************	. 01., 20			2823			

Please find below and/or attached an Office communication concerning this application or proceeding.

	I A At At At	- M	
	Application No.	Applicant(s)	
Office Action Summer:	09/709,483	KWON, OH-NAM	
Office Action Summary	Examiner	Art Unit	
	Thanh V Pham	2823	
The MAILING DATE of this communication appeared for Reply	opears on the cover sheet	vitn the correspondence address	
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statu - Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b). Status		a reply be timely filed irty (30) days will be considered timely. DNTHS from the mailing date of this communication. ABANDONED (35 U.S.C. § 133).	
1) Responsive to communication(s) filed on 25	5 August 2003 .		
2a) ☐ This action is FINAL. 2b) ☒ T	his action is non-final.		
3) Since this application is in condition for allow closed in accordance with the practice unde Disposition of Claims			5
4)⊠ Claim(s) <u>1-13</u> is/are pending in the application	on.		
4a) Of the above claim(s) is/are withdr	awn from consideration.		
5) Claim(s) is/are allowed.			
6)⊠ Claim(s) <u>1-13</u> is/are rejected.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction and	or election requirement.		
Application Papers			
9)⊠ The specification is objected to by the Examin			
10) The drawing(s) filed on is/are: a) acc			
Applicant may not request that any objection to t			
11) The proposed drawing correction filed on If approved, corrected drawings are required in r		disapproved by the Examiner.	
12) The oath or declaration is objected to by the E	• •		
Priority under 35 U.S.C. §§ 119 and 120	examinor.		
13) Acknowledgment is made of a claim for foreign	an priority under 35 LLS C	& 119(a)-(d) or (f)	
a) ☐ All b) ☐ Some * c) ☐ None of:	gn phonty under 60 0.0.c	. 3 1 10(a)-(a) of (i).	
1. Certified copies of the priority documer	nts have been received		
2. Certified copies of the priority documer		Application No	
3. Copies of the certified copies of the pri application from the International E	iority documents have bee Bureau (PCT Rule 17.2(a))	n received in this National Stage	
* See the attached detailed Office action for a list	•		>
14) Acknowledgment is made of a claim for domes			ווע).
 a) The translation of the foreign language p 15) Acknowledgment is made of a claim for domes 	• -		
Attachment(s)			
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449) Paper No(s) 	5) Notice	w Summary (PTO-413) Paper No(s) of Informal Patent Application (PTO-152)	
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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 08/25/03 has been entered.

Response to Arguments

2. Applicant's arguments dated 08/25/03 have been fully considered but they are not persuasive.

Applicant argues in the statement on page 3 of the Remark: 'In the specification, the paragraph beginning at page 3, line 4 has been amended to explicitly recite a feature of LCD devices that was implicit in the original specification and that is well known in the art. Therefore, this amendment does not add new matter'.

The examiner agrees that glass substrate is well known in the art, however other materials are also well known for LCD substrate as provided in the last office action mailed 06/27/03 (Nishiki's US 2003/0030760 A1 [0018]). Therefore, "glass" substrate is not considered as implicitly disclosed in the original disclosure, and although it is not



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constitute a limitation in any patentable sense, it is an added new matter to the specification. The amendment to the specification is not entered.

Further, with respect to the rejection under 35 USC 102, the aerogels 40/42 of Havemann et al. -used in the previous rejection- had been defined as glass in the art at the time the invention was made in such an article as provided herewith (Chan's abstract).

Response to Amendment

Specification

3. The amendment filed 08/25/03 is objected to under 35 U.S.C. 132 because it introduces new matter into the disclosure. 35 U.S.C. 132 states that no amendment shall introduce new matter into the disclosure of the invention. The added material which is not supported by the original disclosure is as follows: "The substrate 1 can be made of a transparent and rigid material such as glass", the paragraph in page 3, line 4.

Applicant is required to cancel the new matter in the reply to this Office Action.

Drawings

4. Figure 4 (same as figure 7 of the Cecilia Y. Mak reference, provided by the applicant) should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The objection to the drawings will not be held in abeyance.



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Claim Rejections

- 5. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
- 6. The newly added limitation has not been treated in the merit.
- 7. Claims 1-13 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. In this instance, glass substrate is new matter as discussed above and in the previous Office Action mailed 02/25/03.
- 8. "Claims 1-2 and 11 are rejected under 35 U.S.C. 102(a)&(e) as being anticipated by Havemann et al. U.S. Patent No. 5,891,804.

The Havemann et al. reference discloses a process for forming thin film conductors comprising forming a photoresist pattern 46 on a *glass* substrate 42/40; etching a portion of the substrate to form a groove 47 *beneath a top surface of the glass substrate* using the photoresist pattern as a mask; depositing a second metal 50 on the substrate, col. 2, lines 13-15, and a height of the second metal being smaller than a depth of the groove, fig. 3b; removing the photoresist pattern on the substrate and the second metal on the photoresist other than in the grove, fig. 3c; and forming the first metal 52 principally copper, col. 2, line 18, on the second metal in the groove, col. 4, lines 54-55, by electroless plating.



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The step of electroless deposition inherently includes the step of preparing a mixed solution having a reductant and a first metal and submerging the substrate in the mixed solution.

9. Claims 4-5, 7-8 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Havemann et al. as applied to claims 1-2 and 11 above, and further in view of Senda et al. U.S. Patent No. 5,364,459.

Re claims 1-2 and 11, the Havemann et al. reference discloses all of the limitation, it does not disclose Ag and Au and the kind of reductant used.

Re claims 2, 4-5, 7-8, 10-11, the Senda et al. reference discloses in the background of the invention that the first metal could be Cu, Ag or Au; the reductant could be formaldehyde; and "the electroless plating is not only applied to formation of a conductive film such as an electrode for an electronic component", col. 1, lines 10-35.

It would have been obvious to one of ordinary skill in the art to apply the known materials as stated by Senda et al. to the method of Havemann et al. because such materials would have been chosen for electroless plating process in the art of making electrode for an electronic device.

10. Claims 3, 6 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Havemann et al. and Senda et al. as applied to claims 1-2, 4-5, 7-8 and 10-11 above, and further in view of Charneski et al. U.S. Patent No. 6,284,652 B1 and/or Eriksson U.S. Patent No. 3,632,435.

Both Havemann et al. and Senda et al. do not disclose the mixed solution for the electroless plating.



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The Charneski et al. reference discloses sulfuric acid and cupric sulfate (col. 8, line 31) used in cooper plating process.

The Eriksson reference discloses the use of silver nitrate, gold chloride with noble metal salts and hydroxide in the mixed solution for electroless plating (col. 5, lines 45-65).

It would have been obvious to one of ordinary skill in the art to apply the known materials as stated by Charneski et al. and/or Eriksson to the method of Havemann et al. and Senda et al. because such materials would have been chosen for the electroless plating process in the art of making electrode for an electronic device in the process of the combination of Havemann et al. and Senda et al.

11. Claims 12-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Havemann et al. and Senda et al. as applied to claims 1-2, 4-5, 7-8, 10 and 11 above, and further in view of JP 05-265040 and applicant's admitted prior art.

The Havemann et al. reference discloses a process for forming thin film conductors comprising forming a photoresist pattern on a substrate using electroless plating, the Senda et al. reference discloses formation of a conductive film such as an electrode for an electronic component using electroless plating.

None of the references disclose the further steps for forming the transistor.

However, JP 05-265040 (provided by applicant) discloses the steps of making gate line in a trench and the applicant admitted prior art that performing the further steps for forming the transistor.

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It would have been obvious to one of ordinary skill in the art to apply the gate electrode of Senda et al. using the method of Havemann et al. into of making a trench gate line and the applicant's admitted prior art of forming transistor as the method and the analogous electrode would be selected in accordance with JP 05-265040 and the applicant's admitted prior art.

Conclusion

- 12. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.
- Any inquiry concerning this communication or earlier communications from the 13. examiner should be directed to Thanh V. Pham whose telephone number is 703-308-2543. The examiner can normally be reached on M-T (6:30-5:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 703-306-2794. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

TvP

10/17/03

Primary Examiner